

Data Sheet

December 2008

Internal control latches and address decoder

Short set-up and hold times

Wide operating voltage: 4.5V to 13.2V

12Vpp analog signal capability

R_{ON} 65Ω max. @ V_{DD}=12V, 25×C

∆R_{ON} ≤ 10Ω @ V_{DD}=12V, 25°C

· Full CMOS switch for low distortion

· Minimum feedthrough and crosstalk

Separate analog and digital reference supplies

Low power consumption ISO-CMOS technology

Applications

Features

- · Key systems
- · PBX systems
- · Mobile radio
- · Test equipment /instrumentation
- · Analog/digital multiplexers
- · Audio/Video switching

Ordering Information

MT8815AP1 44 Pin PLCC* Tubes
MT8815APR 44 Pin PLCC Tape & Reel
MT8815APR1 44 Pin PLCC* Tape & Reel
MT8815AE1 40 Pin PDIP* Tubes

*Pb Free Matte Tin

-40°C to +85°C

Description

The Zarlink MT8815 is fabricated in Zarlink's ISO-CMOS technology providing low power dissipation and high reliability. The device contains a 8 x 12 array of crosspoint switches along with a 7 to 96 line decoder and latch circuits. Any one of the 96 switches can be addressed by selecting the appropriate seven address bits. The selected switch can be turned on or off by applying a logical one or zero to the DATA input. V_{SS} is the ground reference of the digital inputs. The range of the analog signal is from V_{DD} to V_{EE} .

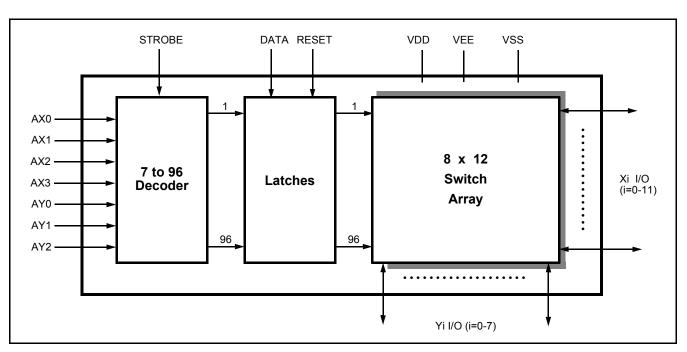


Figure 1 - Functional Block Diagram

Change Summary

Changes from August 2005 to December 2008 issue.

Page	ltem	Change
1	Ordering Information	MT8815AE removed - obsolete. Added pb free part numbers.

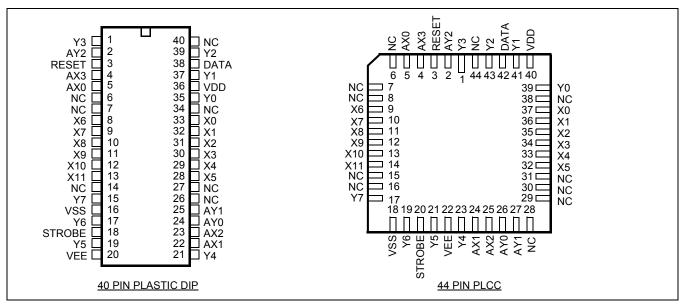


Figure 2 - Pin Connections

Pin Description

Pir	า #	Name	Description				
PDIP	PLCC	INAIIIC	Description				
1	1	Y3	Y3 Analog (Input/Output): this is connected to the Y3 column of the switch array.				
2	2	AY2	Y2 Address Line (Input).				
3	3	RESET	Master RESET (Input): this is used to turn off all switches. Active High.				
4,5	4,5	AX3,AX0	X3 and X0 Address Lines (Inputs): these are used to select X3 and X0 rows of switches.				
6,7	6-8	NC	No Connection.				
8-13	9-14	X6-X11	X6-X11 Analog (Inputs/Outputs): these are connected to the X6-X11 rows of the switch array.				
14	15,16	NC	No Connection				
15	17	Y7	Y7 Analog (Input/Output): this is connected to the Y7 column of the switch array.				
16	18	V _{SS}	Digital Ground Reference (Input).				

Pin Description

Piı	n #	Name	Description				
PDIP	PLCC	Name	Description				
17	19	Y6	Y6 Analog (Input/Output): this is connected to the Y6 column of the switch array.				
18	20	STROBE	STROBE (Input) : enables function selected by address and data. Address must be stable before STROBE goes high and DATA must be stable on the falling edge of the STROBE. Active High.				
19	21	Y5	Y5 Analog (Input/Output): this is connected to the Y5 column of the switch array.				
20	22	V _{EE}	Negative Power Supply.				
21	23	Y4	Y4 Analog (Input/Output): this is connected to the Y4 column of the switch array.				
22, 23	24,25	AX1,AX2	X1 and X2 Address Lines (Inputs).				
24, 25	26,27	AY0,AY1	Y0 and Y1 Address Lines (Inputs).				
26, 27	28-31	NC	No Connection.				
28 - 33	32-37	X5-X0	X5-X0 Analog (Inputs/Outputs): these are connected to the X5-X0 rows of the switch array.				
34	38	NC	No Connection.				
35	39	Y0	Y0 Analog (Input/Output): this is connected to the Y0 column of the switch array.				
36	40	V _{DD}	Positive Power Supply.				
37	41	Y1	Y1 Analog (Input/Output): this is connected to the Y1 column of the switch array.				
38	42	DATA	DATA (Input) : a logic high input will turn on the selected switch and a logic low will turn off the selected switch. Active High.				
39	43	Y2	Y2 Analog (Input/Output): this is connected to the Y2 column of the switch array.				
40	44	NC	No Connection.				

Functional Description

The MT8815 is an analog switch matrix with an array size of 8×12 . The switch array is arranged such that there are 8 columns by 12 rows. The columns are referred to as the Y inputs/outputs and the rows are the X inputs/outputs. The crosspoint analog switch array will interconnect any X I/O with any Y I/O when turned on and provide a high degree of isolation when turned off. The control memory consists of a 96 bit write only RAM in which the bits are selected by the address inputs (AY0-AY2, AX0-AX3). Data is presented to the memory on the DATA input. Data is asynchronously written into memory whenever the STROBE input is high and is latched on the falling edge of STROBE. A logical "1" written into a memory cell turns the corresponding crosspoint switch on and a logical "0" turns the crosspoint off. Only the crosspoint switches corresponding to the addressed memory location are altered when data is written into memory. The remaining switches retain their previous states. Any combination of X and Y inputs/outputs can be interconnected by establishing appropriate patterns in the control memory. A logical "1" on the RESET input will asynchronously return all memory locations to logical "0" turning off all crosspoint switches. Two voltage reference pins (V_{SS} and V_{EE}) are provided for the MT8815 to enable switching of negative analog signals. The range for digital signals is from V_{DD} to V_{SS} while the range for analog signals is from V_{DD} to V_{EE} . V_{SS} and V_{EE} pins can be tied together if a single voltage reference is needed.

Address Decode

The seven address inputs along with the STROBE are logically ANDed to form an enable signal for the resettable transparent latches. The DATA input is buffered and is used as the input to all latches. To write to a location, RESET must be low while the address and data are set up. Then the STROBE input is set high and then low causing the data to be latched. The data can be changed while STROBE is high, however, the corresponding switch will turn on and off in accordance with the DATA input. DATA must be stable on the falling edge of STROBE in order for correct data to be written to the latch.

$\textbf{Absolute Maximum Ratings*-} \ \textit{Voltages are with respect to V}_{\textit{EE}} \ \textit{unless otherwise stated}.$

	Parameter	Symbol	Min.	Max.	Units
1	Supply Voltage	V_{DD} V_{SS}	-0.3 -0.3	15.0 V _{DD} +0.3	V V
2	Analog Input Voltage	V_{INA}	-0.3	V _{DD} +0.3	V
3	Digital Input Voltage	V _{IN}	V _{SS} -0.3	V _{DD} +0.3	V
4	Current on any I/O Pin	I		±15	mA
5	Storage Temperature	T _S	-65	+150	°C
6	Package Power Dissipation PLASTIC DIP	P_{D}		0.6	W

^{*} Exceeding these values may cause permanent damage. Functional operation under these conditions is not implied.

$\textbf{Recommended Operating Conditions} \text{ - Voltages are with respect to V}_{\text{EE}} \text{ unless otherwise stated}.$

	Characteristics	Sym.	Min.	Тур.	Max.	Units	Test Conditions
1	Operating Temperature	T _O	-40	25	85	°C	
2	Supply Voltage	V _{DD} V _{SS}	4.5 V _{EE}		13.2 V _{DD} -4.5	V V	
3	Analog Input Voltage	V_{INA}	V_{EE}		V_{DD}	V	
4	Digital Input Voltage	V _{IN}	V_{SS}		V_{DD}	V	

DC Electrical Characteristics † - Voltages are with respect to V_{EE} = V_{SS} =0V, V_{DD} =12V unless otherwise stated.

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	Quiescent Supply Current	I _{DD}		1	100	μА	All digital inputs at V_{IN} = V_{SS} or V_{DD}
				0.4	1.5	mA	All digital inputs at V_{IN} =2.4V + V_{SS} ; V_{SS} =7.0V
				5	15	mA	All digital inputs at V _{IN} =3.4V
2	Off-state Leakage Current (See G.9 in Appendix)	l _{OFF}		±1	±500	nA	$IV_{Xi} - V_{Yj}I = V_{DD} - V_{EE}$ See Appendix, Fig. A.1
3	Input Logic "0" level	V _{IL}			0.8+V _{SS}	V	V _{SS} =7.5V; V _{EE} =0V
4	Input Logic "1" level	V _{IH}	2.0+V _{SS}			V	V_{SS} =6.5V; V_{EE} =0V
5	Input Logic "1" level	V _{IH}	3.3			V	
6	Input Leakage (digital pins)	I _{LEAK}		0.1	10	μА	All digital inputs at $V_{IN} = V_{SS}$ or V_{DD}

[†] DC Electrical Characteristics are over recommended temperature range. ‡ Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing.

$\textbf{DC Electrical Characteristics-Switch Resistance} \text{ - } V_{DC} \text{ is the external DC offset applied at the analog I/O pins.}$

	Characteristics	Sym	25	s°C	70)°C	85°C		85°C		Units	Test Conditions
			Тур.	Max.	Тур.	Max.	Тур.	Max.				
1	On-state V_{DD} =12V Resistance V_{DD} =10V V_{DD} = 5V (See G.1, G.2, G.3 in Appendix)	R _{ON}	45 55 120	65 75 185		75 85 215		80 90 225	Ω Ω Ω	$V_{SS}=V_{EE}=0V, V_{DC}=V_{DD}/2,$ $IV_{Xi}-V_{Yj}I=0.4V$ See Appendix, Fig. A.2		
2	Difference in on-state resistance between two switches (See G.4 in Appendix)	ΔR _{ON}	5	10		10		10	Ω	V_{DD} =12V, V_{SS} = V_{EE} =0, V_{DC} = V_{DD} /2, IV_{Xi} - $V_{Yj}I$ = 0.4V See Appendix, Fig. A.2		

AC Electrical Characteristics † - Crosspoint Performance-Voltages are with respect to V_{DD} =5V, V_{SS} =0V, V_{EE} =-7V, unless otherwise stated.

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	Switch I/O Capacitance	C _S		20		pF	f=1 MHz
2	Feedthrough Capacitance	C _F		0.2		pF	f=1 MHz
3	Frequency Response Channel "ON" 20LOG(V _{OUT} /V _{Xi})=-3dB	F _{3dB}		45		MHz	Switch is "ON"; V_{INA} = 2Vpp sinewave; R_L = 1k Ω See Appendix, Fig. A.3
4	Total Harmonic Distortion (See G.5, G.6 in Appendix)	THD		0.01		%	Switch is "ON"; V_{INA} = 2Vpp sinewave f= 1kHz; R_L =1k Ω
5	Feedthrough Channel "OFF" Feed.=20LOG (V _{OUT} /V _{Xi}) (See G.8 in Appendix)	FDT		-95		dB	All Switches "OFF"; V_{INA} = 2Vpp sinewave f= 1kHz; R_L = 1k Ω . See Appendix, Fig. A.4
6	Crosstalk between any two channels for switches Xi-Yi and	X _{talk}		-45		dB	V_{INA} =2Vpp sinewave f= 10MHz; R_L = 75 Ω .
	Xj-Yj.			-90		dB	V_{INA} =2Vpp sinewave f= 10kHz; R _L = 600Ω.
	Xtalk=20LOG (V _{Yj} /V _{Xi}). (See G.7 in Appendix).			-85		dB	V_{INA} =2Vpp sinewave f= 10kHz; R _L = 1kΩ.
				-80		dB	V_{INA} =2Vpp sinewave f= 1kHz; R _L = 10kΩ. Refer to Appendix, Fig. A.5 for test circuit.
7	Propagation delay through switch	t _{PS}		tual and I/C	30	ns	R _L =1kΩ; C _L =50pF

[†] Timing is over recommended temperature range. See Fig. 3 for control and I/O timing details.
‡ Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing.
Crosstalk measurements are for Plastic DIPS only, crosstalk values for PLCC packages are approximately 5 dB better.

 $\textbf{AC Electrical Characteristics}^{\dagger} \textbf{-Control and I/O Timings} \textbf{-} \textit{Voltages are with respect to V}_{DD} \textbf{=} 5 \textit{V}, \textit{V}_{SS} \textbf{=} 0 \textit{V}, \textit{V}_{SS} \textbf{=$ V_{EE}=-7V, unless otherwise stated.

	Characteristics	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions
1	Control Input crosstalk to switch (for DATA, STROBE, Address)	CX _{talk}		30		mVpp	V_{IN} =3V squarewave; R _{IN} =1kΩ, R _L =10kΩ. See Appendix, Fig. A.6
2	Digital Input Capacitance	C _{DI}		10		pF	f=1MHz
3	Switching Frequency	F _O			20	MHz	
4	Setup Time DATA to STROBE	t _{DS}	10			ns	R_L = 1k Ω , C_L =50pF ¹
5	Hold Time DATA to STROBE	t _{DH}	10			ns	R_L = 1k Ω , C_L =50pF ¹
6	Setup Time Address to STROBE	t _{AS}	10			ns	$R_L = 1k\Omega$, $C_L = 50pF^{-1}$
7	Hold Time Address to STROBE	t _{AH}	10			ns	R_L = 1k Ω , C_L =50pF ¹
8	STROBE Pulse Width	t _{SPW}	20			ns	$R_L = 1k\Omega$, $C_L = 50pF^{-1}$
9	RESET Pulse Width	t _{RPW}	40			ns	R_L = 1k Ω , C_L =50pF ¹
10	STROBE to Switch Status Delay	t _S		40	100	ns	$R_L = 1k\Omega$, $C_L = 50pF^{-1}$
11	DATA to Switch Status Delay	t _D		50	100	ns	$R_L = 1k\Omega$, $C_L = 50pF^{-1}$
12	RESET to Switch Status Delay	t _R		35	100	ns	R_L = 1k Ω , C_L =50pF ¹

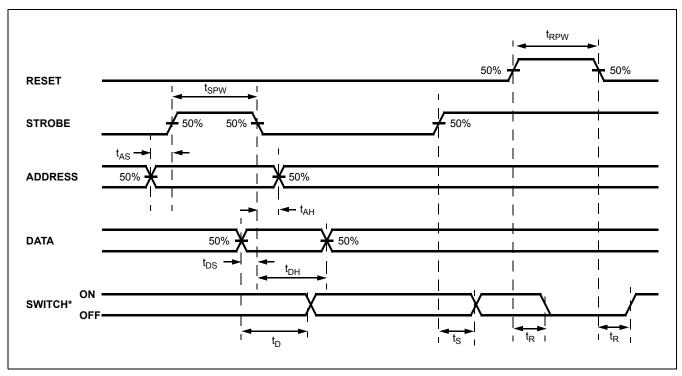


Figure 3 - Control Memory Timing Diagram

[†] Timing is over recommended temperature range. See Fig. 3 for control and I/O timing details.

Digital Input rise time (tr) and fall time (tf) = 5ns.

‡ Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing.

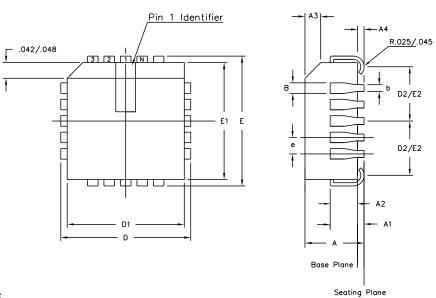
1 Refer to Appendix, Fig. A.7 for test circuit.

^{*} See Appendix, Fig. A.7 for switching waveform

AX0	AX1	AX2	AX3	AY0	AY1	AY2	Connection
0	0	0	0	0	0	0	X0-Y0
1	0	0	0	0	0	0	X1-Y0
0	1	0	0	0	0	0	X2-Y0
1	1	0	0	0	0	0	X3-Y0
0	0	1	0	0	0	0	X4-Y0
1	0	1	0	0	0	0	X5-Y0 ①
0	1	1	0	0	0	0	No Connection
1	1	1	0	0	0	0	No Connection
0	0	0	1	0	0	0	X6-Y0
1	0	0	1	0	0	0	X7-Y0
0	1	0	1	0	0	0	X8-Y0
1	1	0	1	0	0	0	X9-Y0
0	0	1	1	0	0	0	X10-Y0
1	0	1	1	0	0	0	X11-Y0 ①
0	1	1	1	0	0	0	No Connection
1	1	1	1	0	0	0	No Connection
0	0	0	0 ↓	1	0	0	X0-Y1 ↓ ↓
1	0	1	1	1	0	0	X11-Y1
0	0	0	0 ↓	0	1	0	X0-Y2 ↓ ↓
1	0	1	1	0	1	0	X11-Y2
0	0	0 ↓	0 ↓	1	1	0	X0-Y3 ↓↓
1	0	1	1	1	1	0	X11-Y3
0	0	0	0	0	0	1	X0-Y4 ↓ ↓
1	0	1	1	0	0	1	X11-Y4
0	0	0	0	1	0	1	X0-Y5 ↓ ↓
1	0	1	1	1	0	1	X11-Y5
0	0	0	0	0	1	1	X0-Y6 ↓ ↓
1	0	1	1	0	1	1	X11-Y6
O O	O	O	O O	1	1	1	X0-Y7 ↓↓
*	•	*	*	*	•	<u> </u>	
1	0	1	1	1	1 	1	X11-Y7

Table 1 - Address Decode Truth Table

 $^{^{\}scriptsize \scriptsize (1)}$ This address has no effect on device status.



	Control Di	imensions	Altern. Dimensions						
Symbol	in inc	hes	in millimetres						
	MIN	MAX	MIN	MAX					
Α	0.165	0.180	4.19	4.57					
A1	0.090	0.120	2.29	3.05					
A2	0.062	0.083	1.57	2.11					
А3	0.042	0.056	1.07	1.42					
Α4	0.020	-	0.51	_					
D	0.685	0.695	17.40	17.65					
D1	0.650	0.656	16.51	16.66					
D2	0.291	0.319	7.39	8.10					
E	0.685	0.695	17.40	17.65					
E1	0.650	0.656	16.51	16.66					
E2	0.291	0.319	7.39	8.10					
В	0.026	0.032	0.66	0.81					
b	0.013	0.021	0.33	0.53					
е	0.050	BSC	1.27	BSC					
		Pin fed	atures						
ND		11							
NE	11								
Ν		44	1						
Note		Squ	are						
Confor	ms to J	EDEC MS		Iss. A					

- Notes:

 1. All dimensions and tolerances conform to ANSI Y14.5M—1982
 2. Dimensions D1 and E1 do not include mould protrusions.
 Allowable mould protrusion is 0.010" per side. Dimensions D1 and E1 include mould protrusion mismatch and are determined at the parting line, that is D1 and E1 are measured at the extreme material condition at the upper or lower parting line.

 3. Controlling dimensions in Inches.

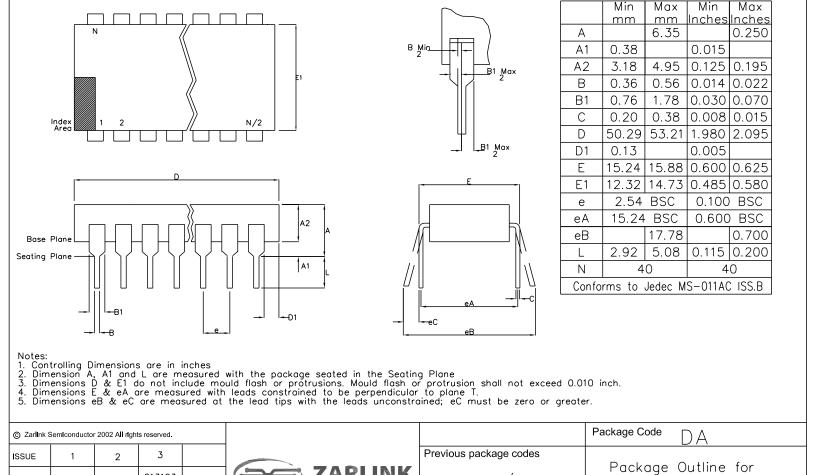
 4. "N" is the number of terminals.

 5. Not To Scale

 6. Dimension R required for 120" minimum bend.

- 6. Dimension R required for 120° minimum bend.

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ISSUE	1	2	3		ZARLINK SEMICONDUCTOR	Previous package codes	Package Outline for
ACN	5958	207470	213094			HP / P	44 lead PLCC
DATE	15Aug94	10Sep99	15Jul02			,	
APPRD.							GPD00003



40 lead PDIP

GPD00073

213103

15Jul02

203533

25Nov97

7010

20Apr95

ACN

DATE

APPRD.



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